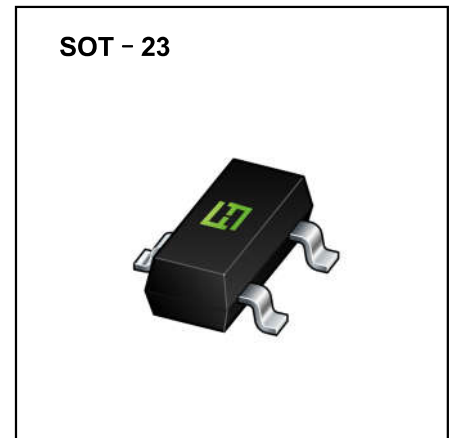


FEATURES

- Complementary to MMBT3906

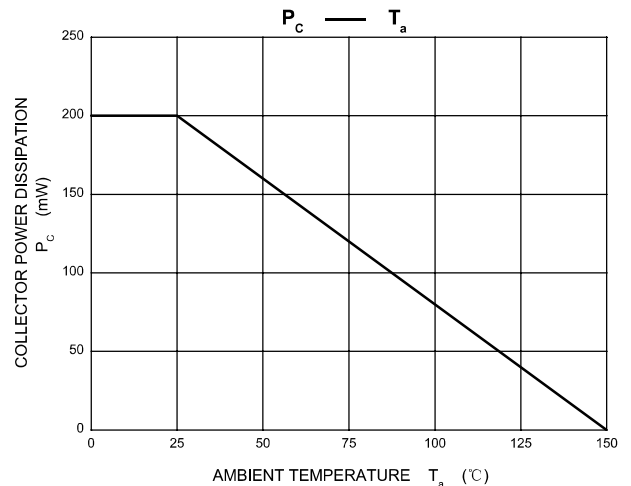
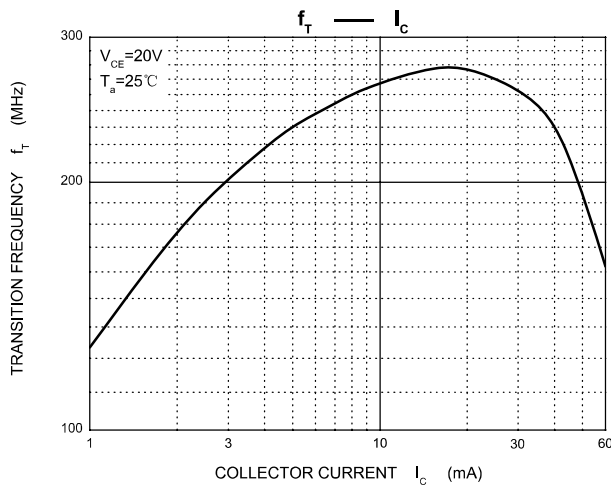
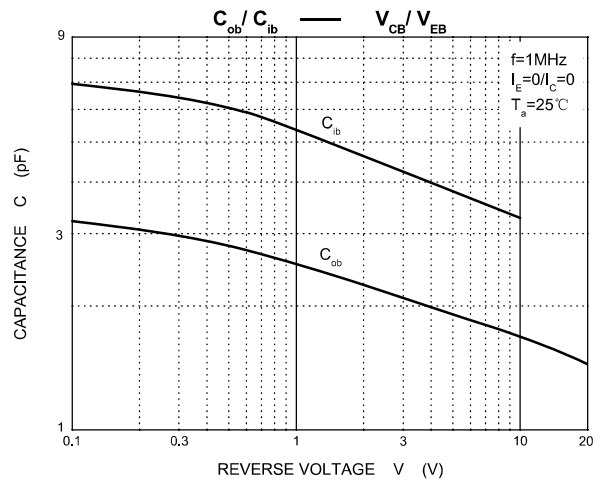
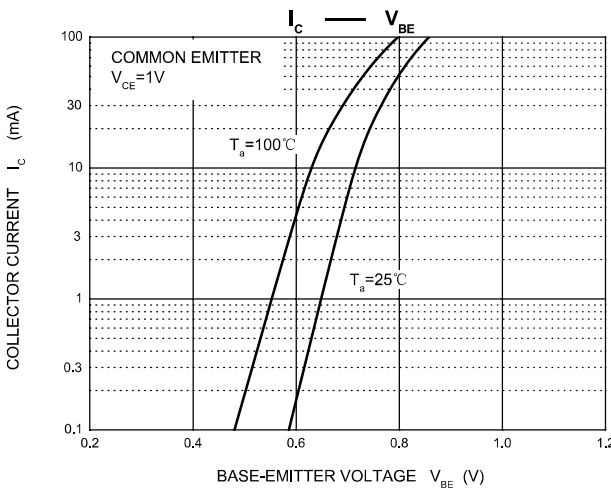
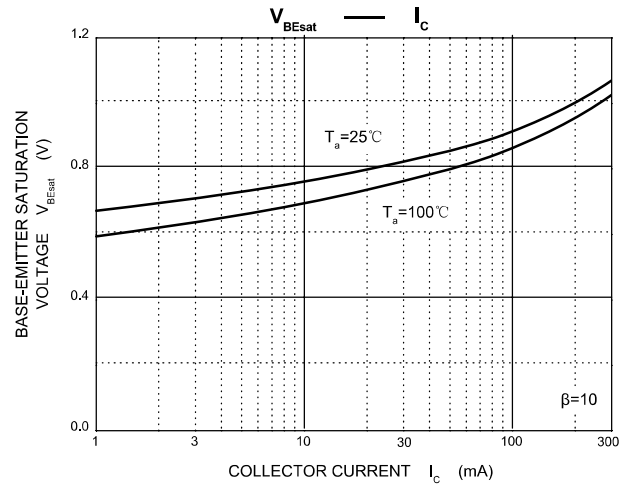
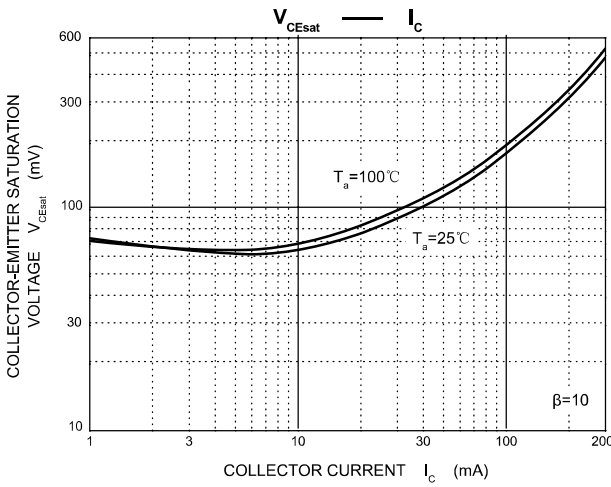
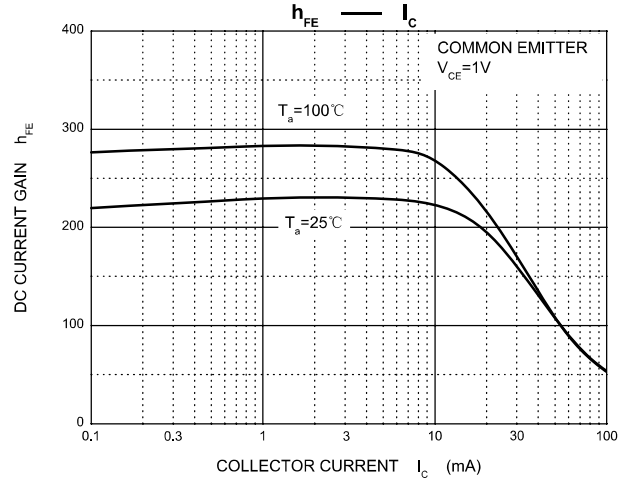
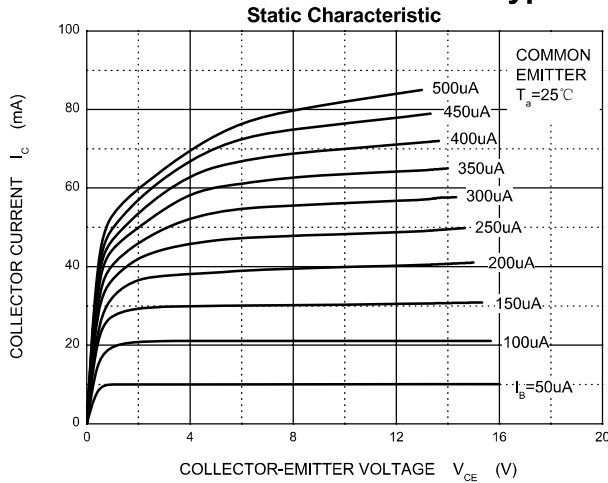
MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-Base Voltage	60	V
V _{CEO}	Collector-Emitter Voltage	40	V
V _{EBO}	Emitter-Base Voltage	6	V
I _C	Collector Current	200	mA
P _C	Collector Power Dissipation	200	mW
R _{θJA}	Thermal Resistance From Junction To Ambient	625	°C/W
T _J	Junction Temperature	150	°C
T _{stg}	Storage Temperature	-55~+150	°C

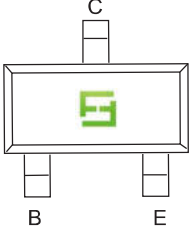
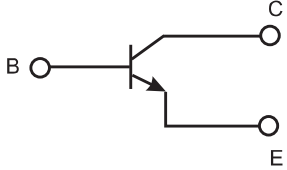

ELECTRICAL CHARACTERISTICS (T_a=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =10μA, I _E =0	60			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA, I _B =0	40			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =10μA, I _C =0	6			V
Collector cut-off current	I _{CEX}	V _{CE} =30V, V _{EB(off)} =3V			50	nA
Collector cut-off current	I _{CBO}	V _{CB} = 60V, I _E =0			100	nA
Emitter cut-off current	I _{EBO}	V _{EB} =5V, I _C =0			100	nA
DC current gain	h _{FE(1)}	V _{CE} =1V, I _C =10mA	100		300	
	h _{FE(2)}	V _{CE} =1V, I _C =50mA	60			
	h _{FE(3)}	V _{CE} =1V, I _C =100mA	30			
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =50mA, I _B =5mA			0.3	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C =50mA, I _B =5mA			0.95	V
Transition frequency	f _T	V _{CE} =20V, I _C =10mA, f=100MHz	300			MHz
Delay time	t _d	V _{CC} =3V, V _{BE(off)} =-0.5V I _C =10mA, I _{B1} =1mA			35	ns
Rise time	t _r	V _{CC} =3V, V _{BE(off)} =-0.5V I _C =10mA, I _{B1} =1mA			35	ns
Storage time	t _s	V _{CC} =3V, I _C =10mA, I _{B1} = I _{B2} =1mA			200	ns
Fall time	t _f	V _{CC} =3V, I _C =10mA, I _{B1} = I _{B2} =1mA			50	ns

Typical Characteristics



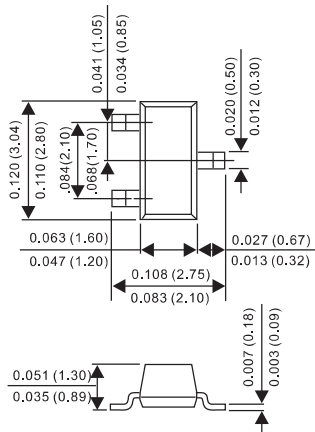
Pinning information

Pin	Simplified outline	Symbol
PinB Base PinC Collector PinE Emitter		

Marking

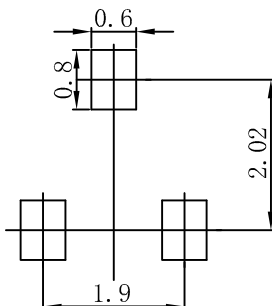
Type number	Marking code
MMBT3904	1AM

SOT-23 Package Outline Dimensions



Dimensions in inches and (millimeters)

SOT-23 Suggested Pad Layout

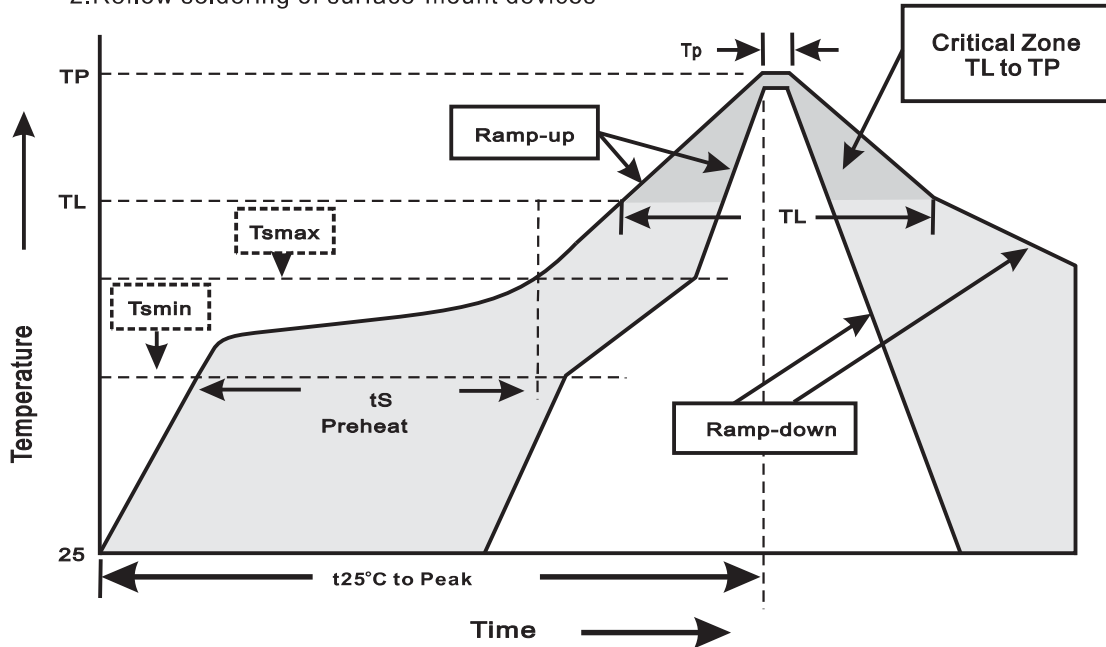


Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes